ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	METHOD FOR SELECTIVE ELECTROPLATING OF SEMICONDUCTOR DEVICE I/O PADS USING A TITANIUM-TUNGSTEN SEED LAYER

Application Number :

Confirmation Number:

First Named Applicant: Tien-Jen Cheng

Attorney Docket Number: FIS920030278US1

Art Unit:

Examiner:

Search string: (5486282 or 5620611 or 6534863 or 5536388 or 6293457 or 6355977 or 6451627 or 20030057551 or 20030082913).pn

US Patent Documents

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
LV	1	5486282	1996-01-23	Datta et al.		205	123
LV	2	5620611	1997-04-15	Datta et al.		216	13
LV	3	6534863	2003-03-18	Walker et al.	B2	257	737
LV	4	5536388	1996-07-16	Dinan et al.		205	670
LV	5	6293457	2001-09-25	Srivastava et al.	B1	228	254
LV	6	6355977	2002-03-12	Nakamura	B1	257	693
LV	7	6451627	2002-09-17	Coffman	B1	438	111

US Published Applications

Note: Applicant is not required to submit a paper copy of cited US Published Applications

init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
LV	1	20030057551	2003-03-27	Datta et al.	A1	257	737
LV	2	20030082913	2003-05-01	Danielson et al.	A1	438	690

Signature

Examiner Name	Date
	9/29/05